Notification Number: 2016		6121	3001	Notification Date:			December 19, 2016	
Title: Datasheet for TSC2007-C		-Q1						
Customer Contact:	PCN Manag	er	Dept:	Quality Se	ervice	es		
Change Type:								
Assembly Site			Design			Wafer Bump Site		
Assembly Process						Wafer Bump Material		
Assembly Materials			Part number change		ЦЦ	Wafer Bump Process		
Mechanical Specification		┥┝	Test Site		ΗH	Wafer Fab Site		
Packing/Shipping/Labeling			Test Process		\mathbb{H}		r Fab Materials	
Notification Details								
Description of Change: Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(s) is updated as seen in the change revision history below:								
TSC2007-Q1								
SBAS545A-SEPTEMBER 2011-REVIS	SED DECEMBER	2016					www.ti.com	
Changes from Original (Septe	ember 2011) t	o Revi	ision A		Page			
Added Device Information ta	able, Specifica	ations s	section, ESD Rating	s table, Recomm	ended	Operatin	g Conditions	
table, Detailed Description s	section, Applic	ation a	and Implementation	section, Power S	upply	Recomme	endations	
section, Layout Guidelines section, Layout Example section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section								
Deleted Ordering Information table; see Package Option Addendum at the end of the data sheet								
Added Automotive Infotainm								
 Deleted On-Chip, Programm 								
Deleted Lead temperature parameters from Absolute Maximum Ratings table								
Moved Power-supply voltage parameters from <i>Electrical Characteristics</i> table to the <i>Recommended Operating</i> Conditions table								
 Added IEC discharge inform 	Added IEC discharge information							
Added Thermal Information table								
Changed R _{eJA} values for PW (TSSOP) From: 86 To: 101.7								
Changed t _{oF} to t _F in Timing Requirements tables								
Changed text in Reference mode to clarify singled-ended operation								
Changed Figure 24 caption text from PINTDAV to PENIRQ								
Added subsections to Throughput Rate and I2C Bus Traffic section to clarify 8-bit and 12-bit operation								
The datasheet number	<u>will</u> be cha	ngin	g					
Device Family				Ch	ange	From:	Change To:	
TSC2007-Q1				SB	AS54	15	SBAS545A	
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/lit/ds/symlink/tsc2007-q1.pdf								
Reason for Change:								
To more accurately refle	ect device	char	acteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device								
Changes to product identification resulting from this notification:								
None.								
Product Affected:								
TSC2007IPWRQ1								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com